

LINEAR TECHNOLOGY MATERIALS DECLARATION

ltc1266is-3.3#trpbf

(Engineering Calculation)

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TOTAL MASS (g) : 0.157083

| COMPONENT MATERIAL | VENDOR/ INDUSTRY NAMES | CONSTITUENT NAME | CAS NUMBER | CONSTITUENT MASS (g) | CONSTITUENT (PPM) OF MATERIAL | CONSTITUENT (PPM) OF TOTAL PKG. | | |
|--------------------------------|----------------------------------|--------------------------------|------------|----------------------|-------------------------------|---------------------------------|----------------|----------------------|
| Active Device | Linear Technology | Silicon (Si) | 7440-21-3 | 0.004103 | 1000000 | 26119.9980469 | | |
| Die Coat | Dow Corning | Silicone | 69430-27-9 | 0.000000 | 0 | 0 | | |
| Lead Frame | Cu | Copper (Cu) | 7440-50-8 | 0.051070 | 975000 | 325115.34375 | | |
| | | Iron (Fe) | 7439-89-6 | 0.001257 | 24000 | 8002.15429688 | | |
| | | Phosphorus (P) | 7723-14-0 | 0.000016 | 300 | 101.857170105 | | |
| | | Zinc (Zn) | 7440-66-6 | 0.000037 | 700 | 235.544723511 | | |
| | | Nickel (Ni) | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Silicon (Si) | 7440-21-3 | 0.000000 | 0 | 0 | | |
| | | Magnesium (Mg) | 7439-95-4 | 0.000000 | 0 | 0 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| Lead Frame Total: | | | | 0.052380 | 1000000 | 333454.90625 | | |
| Plating | PMI | Exter. Plating Pb | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Exter. Plating Sn | 7440-31-5 | 0.002954 | 1000000 | 18803.4960938 | | |
| | | External Plating Total: | | | | 0.002954 | 1000000 | 18803.4960938 |
| | | Inter. Plating Ni | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Inter. Plating Ag | 7440-22-4 | 0.000419 | 1000000 | 2667.38476562 | | |
| Internal Plating Total: | | | | 0.000419 | 1000000 | 2667.38476562 | | |
| Die Attach | ELECTRICALLY CONDUCTIVE ADHESIVE | Silver (Ag) | 7440-22-4 | 0.001142 | 750000 | 7270.05517578 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| | | Lead (Pb) | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.000000 | 0 | 0 | | |
| | | Indium (In) | 7440-74-6 | 0.000000 | 0 | 0 | | |
| | | Metal Oxide | | 0.000000 | 0 | 0 | | |
| | | Antimony (Sb) | 7440-36-0 | 0.000000 | 0 | 0 | | |
| | | Resin (EP) | | 0.000381 | 250000 | 2425.47387695 | | |
| Die Attach Total: | | | | 0.001523 | 1000000 | 9695.52929688 | | |
| Encapsulation | MULTI-AROMATIC RESIN Br/Sb FREE | Resin (EP) | | 0.012389 | 130000 | 78869.2734375 | | |
| | | Bromine (Br) | 40039-93-8 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.079099 | 830000 | 503550 | | |
| | | Antimony Trioxide (Sb2O3) | 1309-64-4 | 0.000000 | 0 | 0 | | |
| | | Metal Hydroxide | | 0.003336 | 35000 | 21237.2207031 | | |
| | | Carbon Black (C) | 1333-86-4 | 0.000477 | 5000 | 3036.61694336 | | |
| | | Encapsulation Total: | | | | 0.095301 | 1000000 | 606693.125 |
| Bond Wire Estimated | AFW/TANAKA/ Kn | Gold (Au) | 7440-57-5 | 0.000403 | 1000000 | 2565.52758789 | | |
| | | | | | TOTAL MASS (g) : | 0.157083 | | |